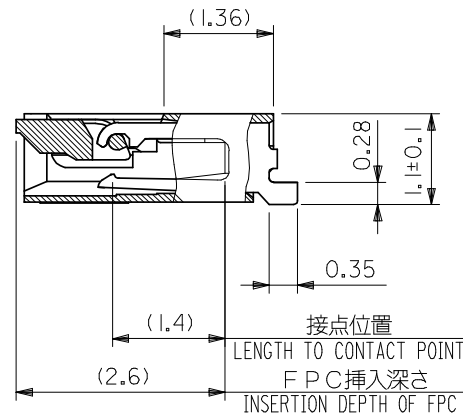
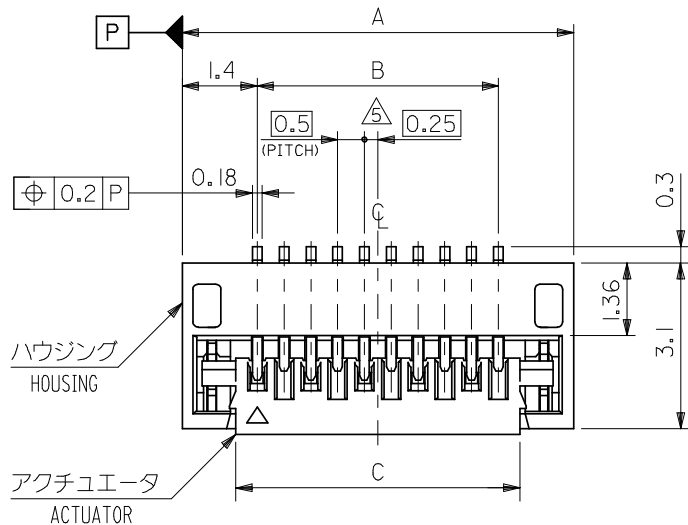
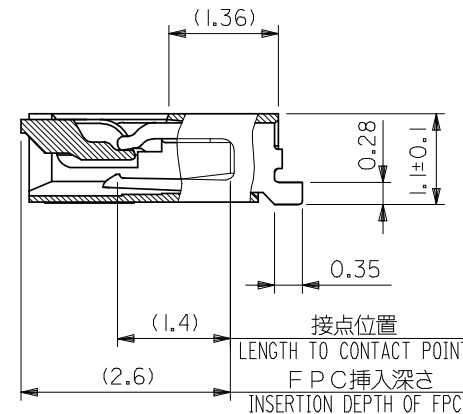
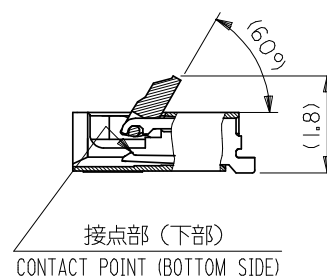
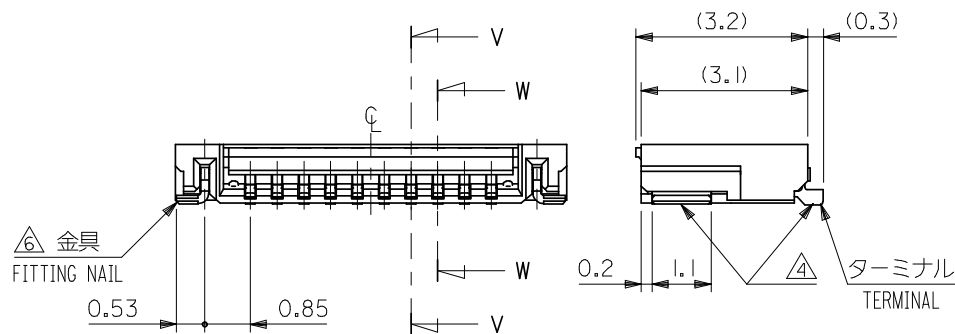




断面 V-V
SECT. V-V
(Scale 15:1)
奇数極
(ODD CIRCUIT)



断面 W-W
SECT. W-W
(Scale 15:1)
偶数極
(EVEN CIRCUIT)



(アクチュエータが開いた状態)
(WHEN ACTUATOR IS OPENED)

12.3	11.5	14.3	51441-2493	51441-2441	24
11.3	10.5	13.3	51441-2293	51441-2241	22
10.3	9.5	12.3	51441-2093	51441-2041	20
9.3	8.5	11.3	51441-1893	51441-1841	18
8.8	8.0	10.8	51441-1793	51441-1741	17
8.3	7.5	10.3	51441-1693	51441-1641	16
6.8	6.0	8.8	51441-1393	51441-1341	13
6.3	5.5	8.3	51441-1293	51441-1241	12
5.8	5.0	7.8	51441-1193	51441-1141	11
5.3	4.5	7.3	51441-1093	51441-1041	10
4.8	4.0	6.8	51441-0993	51441-0941	9
4.3	3.5	6.3	51441-0893	51441-0841	8
3.8	3.0	5.8	51441-0793	51441-0741	7
3.3	2.5	5.3	51441-0693	51441-0641	6
C	B	A	EMBOSSD TAPE ORDER No. オーダー番号	製品番号 MATERIAL No.	極数 CIRCUIT

REVISED EC NO: J2008-4048 DRWN:WABEI 2008/06/13 CHKD:THARUYAMA 2008/06/16 APPR:NUKITA 2008/06/16	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 10:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
		10 UNDER	±0.2	DRAWN BY M. HAYASHI	DATE 2003/12/22	TITLE 0.5 FPC CONN. E/O HSG ASSY BTM CONT(H=1.1) -LEAD FREE-				
		10 OVER 30 UNDER	±0.25	CHECKED BY K. TOJO	DATE 2003/12/22					
		30 OVER	±0.3	APPROVED BY M. SASAO	DATE 2003/12/22	MOLEX MOLEX INCORPORATED				
		ANGULAR ±3 °		MATERIAL NO. SEE TABLE		DOCUMENT NO. SD-51441-007			SHEET NO. 1 OF 2	
	REV	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION						

F

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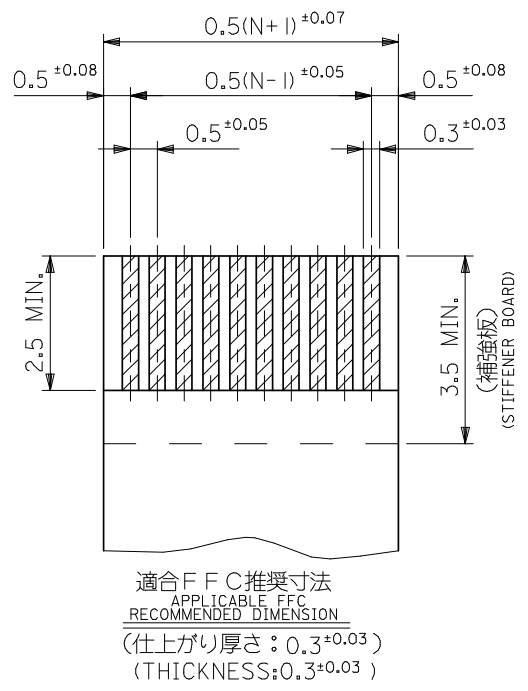
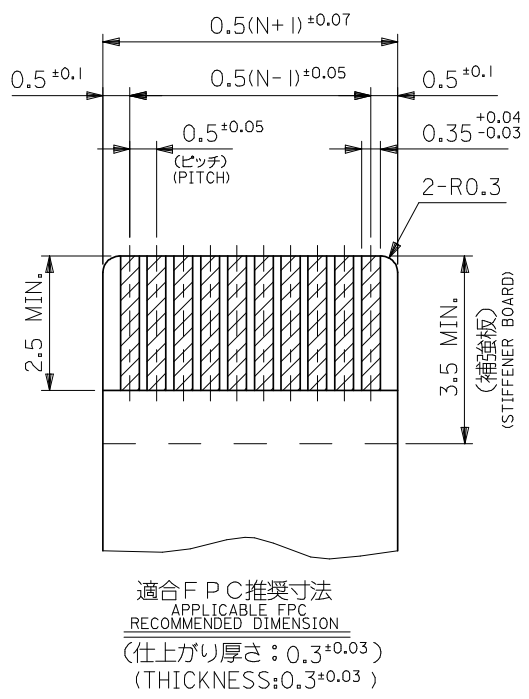
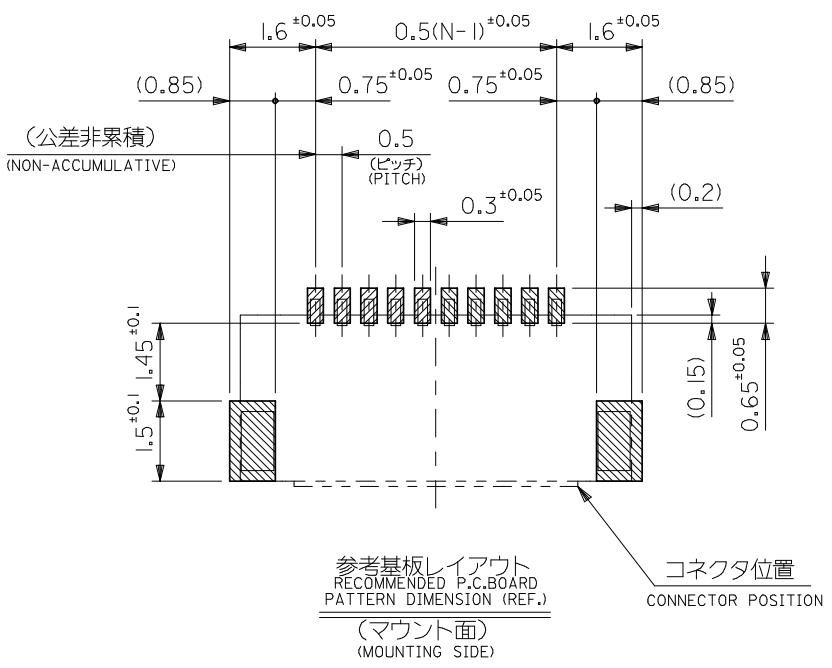
E

D

C

B

A



注記 NOTES

1. 使用材料 MATERIAL

ハウジング : 液晶ポリマー ガラス充填、UL94V-0 (ベージュ)
HOUSING : LIQUID CRYSTAL POLYMER GLASS FILLED, UL94V-0(BEIGE)
アクチュエータ : ポリフェニレンサルファイド ガラス充填、UL94V-0 (黒)
ACTUATOR : POLYPHENYLENE SULFIDE GLASS FILLED, UL94V-0(BLACK)
ターミナル : リン青銅 (t=0.18)
TERMINAL : PHOSPOR BRONZE
金具 : リン青銅 (t=0.15)
FITTING NAIL : PHOSPOR BRONZE

2. メッキ仕様 PLATING

ターミナル TERMINAL
ニッケル下地錫ピスマスメッキ
TIN-BISMUTH (LEAD FREE) OVER NICKEL PLATING
金具 FITTING NAIL
ニッケル下地錫メッキ
PURE TIN (LEAD FREE) OVER NICKEL PLATING

3. エンボステープ梱包時は、アクチュエータが閉じた状態とする。
IN THE PACKAGE, ACTUATOR OF PART NO.51441-***II SHOULD BE CLOSED.
△ソルダーテール及び金具の平坦度は、0.1以下。
SOLDER TAIL AND FITTING NAIL COPLANARITY TO BE 0.1 MAXIMUM.
△偶数極に適用。
APPLY FOR EVEN CIRCUIT.
△パターンはくり止め用金具
FITTING NAIL FOR PREVENTION OF PEELING OF PCB PATTERN.
7. この製品は 51441-***II 及び 51441-***3I の鉛フリー品です。
THIS PRODUCT IS LEAD FREE ITEM OF 51441-***II AND 51441-***3I.

FPC/FFCについて:

打抜き方向は導体側から補強板側を推奨いたします。
導体部については軟銅箔35マイクロメートルまたは50マイクロメートルを推奨いたします。
ABOUT FPC/FFC
RECOMMENDED PUNCHER DIRECTION : FROM CONDUCTOR SIDE TO STIFFENER FILM SIDE.
RECOMMENDED CONDUCTOR SPEC :
THICKNESS OF SOFT COPPER FOIL : 35 MICROMETER OR 50 MICROMETER

FPCについて:

補強フィルム材質はポリイミドを推奨します。
接着剤は熱硬化接着剤を推奨します。
ABOUT FPC
RECOMMENDED MATERIAL :
STIFFENER FILM : POLYIMIDE
BONDING AGENT : THERMOSETTING BONDING AGENT

REVISED EC NO: J2008-4048 DRWN:WABEI 2008/06/13 CHKD:THARUYAMA 2008/06/16 APPR:NUKITA 2008/06/16	DESCRIPTION REV	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		51441-***41		MODEL NO.		
						SCALE 10:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
		10 UNDER ±0.2		DRAWN BY DATE M. HAYASHI 2003/12/22		TITLE 0.5 FPC CONN. E/O HSG ASSY BTM CONT(H=1.1) -LEAD FREE-				
		10 OVER 30 UNDER ±0.25		CHECKED BY DATE K. TOJO 2003/12/22						
		30 OVER ±0.3		APPROVED BY DATE M. SASAO 2003/12/22		MOLEX MOLEX INCORPORATED				
		ANGULAR ±3 °		MATERIAL NO. SEE SHEET 1						
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3 THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION						

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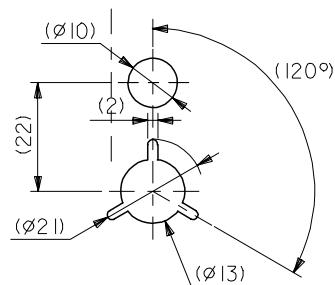
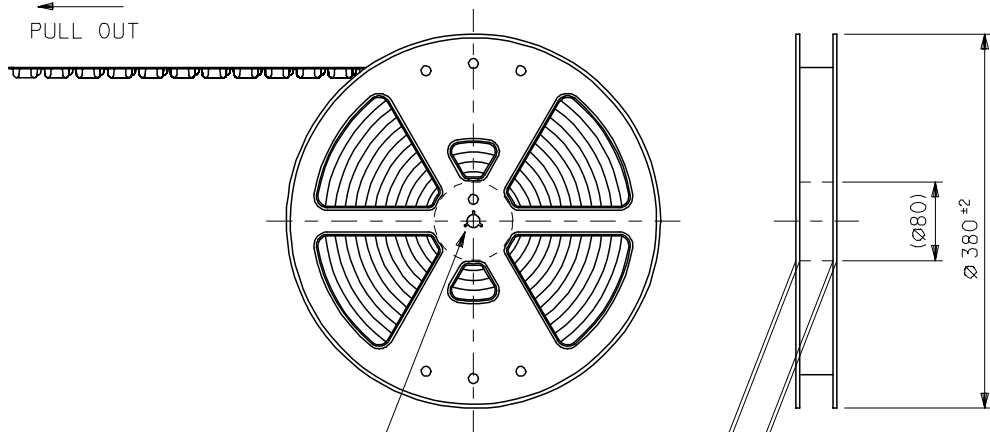
D

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A

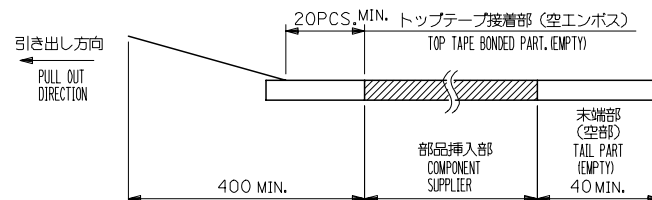
引き出し方向
PULL OUT



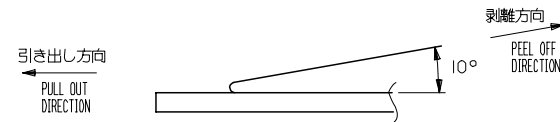
DETAIL "F"

注記 NOTES

- 製品詳細寸法については、図面SD-51441-007を参照下さい。
RE DETAILED DIMENSION, SEE SD-51441-007.
- 梱包数量：3000個/リール
NUMBER OF CONNECTORS : 3000PCS/REEL
- リードテープ長さ LEAD TAPE LENGTH

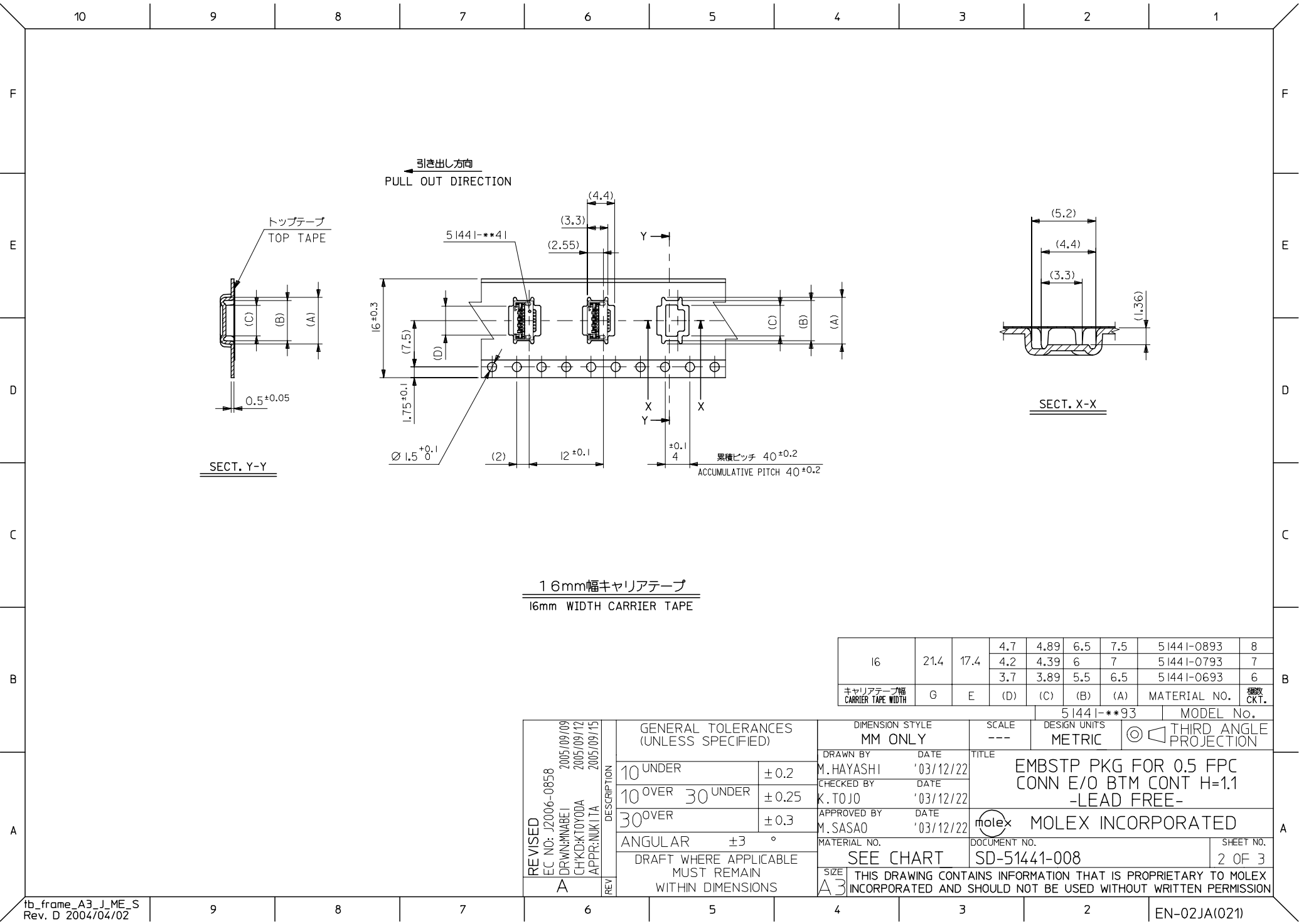


- トップテープの剥離強度：0.1N～1.3N {10.2gf～130gf}
(剥離方向は下図参照)
尚、本規格値は出荷時に適用。(但し、輸送時に剥離が発生しないこと。)
PEELING OFF FORCE OF TOP TAPE : 0.1N ~ 1.3N(10gf ~ 130gf)
(PEELING DIRECTION AS SHOWN IN FOLLOWING FIG.)
THIS REQUIREMENT SHOULD BE APPLIED AT SHIPMENT.
PEEL OFF SHOULD NOT BE ALLOWED, DURING TRANSPORTATION.



- 材料 (MATERIAL)
キャリアテープ (CARRIER TAPE)：ポリプロピレン (POLYPROPYLENE)
トップテープ (TOP TAPE)：PET, PE, PEF
リール (REEL)：ポリスチレン (PS) <リサイクル材を含む>
POLYSTYRENE(PS) <RECYCLE MATERIAL CONTAINED>
- この製品は51441-**-90及び51441-**-92の鉛フリー品です。
THIS PRODUCT IS LEAD FREE ITEM OF 51441-**-90 AND 51441-**-92.

REVISED	EC NO: J2006-0858		2005/09/09		DRWN:MABE1		2005/09/12		CHKDK:TOYODA		2005/09/15		APPR:NUKITA		2005/09/15		DESCRIPTION		REV									
	GENERAL TOLERANCES (UNLESS SPECIFIED)																DIMENSION STYLE MM ONLY				SCALE ---		DESIGN UNITS METRIC				THIRD ANGLE PROJECTION	
	10 UNDER						± 0.2						DRAWN BY M. HAYASHI				DATE '03/12/22				TITLE EMBSTP PKG FOR 0.5 FPC CONN E/O BTM CONT H=1.1 -LEAD FREE-							
	10 OVER 30 UNDER						± 0.25						CHECKED BY K. TOJO				DATE '03/12/22											
	30 OVER						± 0.3						APPROVED BY M. SASAO				DATE '03/12/22				 MOLEX INCORPORATED							
	ANGULAR ±3 °						MATERIAL NO.				DOCUMENT NO.				SHEET NO.													
	DRAFT WHERE APPLICABLE						SEE CHART				SD-51441-008				1 OF 3													
	MUST REMAIN						SIZE A3				THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX																	
	WITHIN DIMENSIONS						INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION																					
	A																											



SECT. Y-Y

SECT. X-X

16mm幅キャリアテープ
16mm WIDTH CARRIER TAPE

16	21.4	17.4	4.7	4.89	6.5	7.5	51441-0893	8
			4.2	4.39	6	7	51441-0793	7
			3.7	3.89	5.5	6.5	51441-0693	6
キャリアテープ幅 CARRIER TAPE WIDTH	G	E	(D)	(C)	(B)	(A)	MATERIAL NO.	模範 CKT.

REVISED EC NO: J2006-0858 DRW: NABEJ CHKD: KTOYODA APPR: NUKITA	DESCRIPTION REV	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
		10 UNDER	±0.2	DRAWN BY M. HAYASHI	DATE '03/12/22	TITLE EMBSTP PKG FOR 0.5 FPC CONN E/O BTM CONT H=1.1 -LEAD FREE-				
		10 OVER 30 UNDER	±0.25	CHECKED BY K. TOJO	DATE '03/12/22					
		30 OVER	±0.3	APPROVED BY M. SASAO	DATE '03/12/22	MOLEX INCORPORATED				
		ANGULAR	±3 °	MATERIAL NO. SEE CHART		DOCUMENT NO. SD-51441-008		SHEET NO. 2 OF 3		
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					

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<http://moschip.ru/get-element>

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Нашей специализацией является поставка электронной компонентной базы двойного назначения, продукции таких производителей как XILINX, Intel (ex.ALTERA), Vicor, Microchip, Texas Instruments, Analog Devices, Mini-Circuits, Amphenol, Glenair.

Сотрудничество с глобальными дистрибьюторами электронных компонентов, предоставляет возможность заказывать и получать с международных складов практически любой перечень компонентов в оптимальные для Вас сроки.

На всех этапах разработки и производства наши партнеры могут получить квалифицированную поддержку опытных инженеров.

Система менеджмента качества компании отвечает требованиям в соответствии с ГОСТ Р ИСО 9001, ГОСТ РВ 0015-002 и ЭС РД 009

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